TOSHIBA CMOS Digital Integrated Circuit Silicon Monolithic

# TC74AC273P,TC74AC273F,TC74AC273FT

#### Octal D-Type Flip Flop with Clear

The TC74AC273 is an advanced high speed CMOS OCTAL D-TYPE FLIP FLOP fabricated with silicon gate and double-layer metal wiring C<sup>2</sup>MOS technology.

It achieves the high speed operation similar to equivalent Bipolar Schottky TTL while maintaining the CMOS low power dissipation.

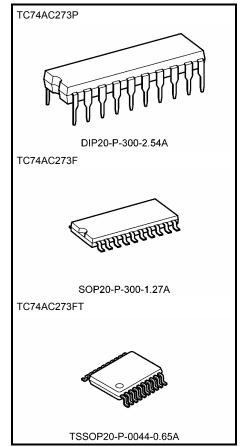
Information signals applied to D inputs are transferred to the Q output on the positive going edge of the clock pulse.

When the  $\overline{\text{CLR}}$  input is held "L", the Q outputs are at a low logic level independent of the other inputs.

All inputs are equipped with protection circuits against static discharge or transient excess voltage.

### **Features**

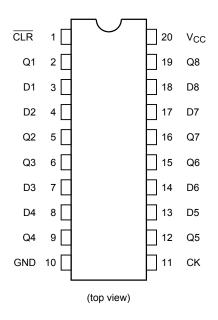
- High speed:  $f_{max} = 170 \text{ MHz}$  (typ.) at  $V_{CC} = 5 \text{ V}$
- Low power dissipation:  $I_{CC} = 8 \mu A \text{ (max)}$  at  $T_{a} = 25 \text{°C}$
- High noise immunity:  $V_{NIH} = V_{NIL} = 28\% V_{CC}$  (min)
- Symmetrical output impedance: | IOH | = IOL = 24 mA (min) Capability of driving 50 Ω transmission lines.
- Balanced propagation delays:  $t_{pLH} \simeq t_{pHL}$
- Wide operating voltage range: VCC (opr) = 2 V to 5.5 V
- Pin and function compatible with 74F273



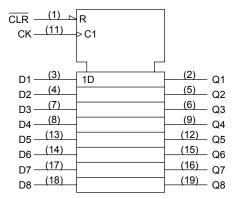
Weight

DIP20-P-300-2.54A : 1.30 g (typ.) SOP20-P-300-1.27A : 0.22 g (typ.) TSSOP20-P-0044-0.65A : 0.08 g (typ.)

## **Pin Assignment**



## **IEC Logic Symbol**

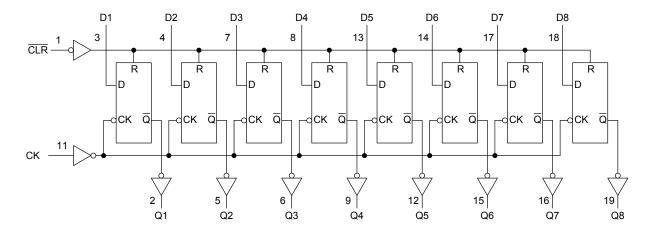


### **Truth Table**

	Inputs		Output	Function			
CLR	CLR D CK		Q	Function			
L	Х	Х	L	Clear			
Н	L		L				
Н	Н		Н	_			
Н	Х		Qn	No Change			

X: Don't care

# **System Diagram**



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## **Absolute Maximum Ratings (Note 1)**

Characteristics	Symbol	Rating	Unit
Supply voltage range	V <sub>CC</sub>	−0.5 to 7.0	V
DC input voltage	V <sub>IN</sub>	-0.5 to V <sub>CC</sub> + 0.5	V
DC output voltage	V <sub>OUT</sub>	-0.5 to V <sub>CC</sub> + 0.5	٧
Input diode current	I <sub>IK</sub>	±20	mA
Output diode current	lok	±50	mA
DC output current	lout	±50	mA
DC V <sub>CC</sub> /ground current	Icc	±200	mA
Power dissipation	PD	500 (DIP) (Note 2)/180 (SOP/TSSOP)	mW
Storage temperature	T <sub>stg</sub>	-65 to 150	°C

Note 1: Exceeding any of the absolute maximum ratings, even briefly, lead to deterioration in IC performance or even destruction.

Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 2: 500 mW in the range of Ta = -40 to  $65^{\circ}$ C. From Ta = 65 to  $85^{\circ}$ C a derating factor of -10 mW/°C should be applied up to 300 mW.

## **Operating Ranges (Note)**

Characteristics	Symbol	Rating	Unit	
Supply voltage	V <sub>CC</sub>	2.0 to 5.5	V	
Input voltage	V <sub>IN</sub>	0 to V <sub>CC</sub>	V	
Output voltage	V <sub>OUT</sub>	0 to V <sub>CC</sub>	V	
Operating temperature	T <sub>opr</sub>	−40 to 85	°C	
Input rise and fall time	dt/dV	0 to 100 (V <sub>CC</sub> = $3.3 \pm 0.3$ V)	ns/V	
input noc and fail time	αναν	0 to 20 (V <sub>CC</sub> = $5 \pm 0.5$ V)	115/ V	

Note: The operating ranges must be maintained to ensure the normal operation of the device.
Unused inputs must be tied to either VCC or GND.



#### **Electrical Characteristics**

#### **DC Characteristics**

Characteristics	Symbol	Test Condition				Га = 25°C	)	Ta = -40 to 85°C		- Unit	
Sharaciensiles Symbol					V <sub>CC</sub>	Min	Тур.	Max	Min		Max
		_		2.0	1.50	_	_	1.50	_		
High-level input voltage	V <sub>IH</sub>			3.0	2.10	_	_	2.10	_	V	
					5.5	3.85	_	_	3.85	_	
					2.0	_	_	0.50	_	0.50	
Low-level input voltage	$V_{IL}$	_		3.0	_	_	0.90	_	0.90	V	
					5.5	_	_	1.65	_	1.65	
	Vон	VIN = VIH or VIL			2.0	1.9	2.0	_	1.9	_	
			$I_{OH} = -50 \mu A$		3.0	2.9	3.0	_	2.9	_	l
High-level output					4.5	4.4	4.5	_	4.4	_	V
voltage			$I_{OH} = -4 \text{ mA}$		3.0	2.58	_	_	2.48	_	·
			$I_{OH} = -24 \text{ mA}$		4.5	3.94	_	_	3.80	_	
			$I_{OH} = -75 \text{ mA}$	(Note)	5.5	_	_	_	3.85	_	
	V <sub>OL</sub>	VIN = VIH or VIL			2.0	_	0.0	0.1	_	0.1	
			$I_{OL} = 50 \ \mu A$		3.0	_	0.0	0.1	_	0.1	
Low-level output					4.5	_	0.0	0.1	_	0.1	- V
voltage			I <sub>OL</sub> = 12 mA		3.0	_	_	0.36	_	0.44	
			$I_{OL} = 24 \text{ mA}$		4.5	_	_	0.36	_	0.44	
			$I_{OL} = 75 \text{ mA}$	(Note)	5.5	_	_	_	_	1.65	
Input leakage current	I <sub>IN</sub>	$V_{IN} = V_{CC}$ or GND		5.5	_	_	±0.1	_	±1.0	μΑ	
Quiescent supply current	I <sub>CC</sub>	V <sub>IN</sub> = V <sub>CC</sub> or GND		5.5	_	_	8.0		80.0	μΑ	

Note: This spec indicates the capability of driving 50  $\Omega$  transmission lines. One output should be tested at a time for a 10 ms maximum duration.

### Timing Requirements (input: $t_r = t_f = 3$ ns)

Characteristics	Symbol	Test Condition	Ta = 25°C	Ta = -40 to 85°C	Unit	
			V <sub>CC</sub> (V)	Limit	Limit	
Minimum pulse width	t <sub>w (L)</sub>		$3.3 \pm 0.3$	8.0	8.0	20
(CK)	t <sub>w (H)</sub>	_	$5.0 \pm 0.5$	5.0	5.0	ns
Minimum pulse width	4		$3.3 \pm 0.3$	7.5	7.5	20
( CLR )	t <sub>w (L)</sub>	_	$5.0 \pm 0.5$	5.0	5.0	ns
Minimum act un time	t <sub>s</sub>	_	$3.3\pm0.3$	8.5	8.5	ns
Minimum set-up time			$5.0 \pm 0.5$	4.5	4.5	
Main income to a lat Alice o			$3.3 \pm 0.3$	0.0	0.0	
Minimum hold time	t <sub>h</sub>	_	$5.0 \pm 0.5$	0.0	0.0	ns
Minimum removal time			$3.3 \pm 0.3$	7.0	7.0	
(CLR)	t <sub>rem</sub>	_	$5.0 \pm 0.5$	3.5	3.5	ns



## AC Characteristics (C<sub>L</sub> = 50 pF, R<sub>L</sub> = 500 $\Omega$ , input: $t_r$ = $t_f$ = 3 ns)

Characteristics	Symbol	Test Condition		Ta = 25°C			Ta = -40 to 85°C		Unit
	, , , ,		V <sub>CC</sub> (V)	Min	Тур.	Max	Min	Max	
Propagation delay time (CK-Q)	t <sub>pLH</sub>	_	$3.3 \pm 0.3$ $5.0 \pm 0.5$	_	9.0 6.5	15.8 9.6	1.0 1.0	18.0 11.0	ns
Propagation delay time ( CLR -Q)	t <sub>pHL</sub>	_	$3.3 \pm 0.3$ $5.0 \pm 0.5$	_	8.0 5.9	14.0 9.2	1.0 1.0	16.0 10.5	ns
Maximum clock frequency	f <sub>max</sub>	_	$3.3 \pm 0.3$ $5.0 \pm 0.5$	55 90	110 150	_	55 90		MHz
Input capacitance	C <sub>IN</sub>	_		_	5	10	_	10	pF
Power dissipation capacitance	C <sub>PD</sub>		(Note)	_	40	_	_	_	pF

Note: CPD is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load.

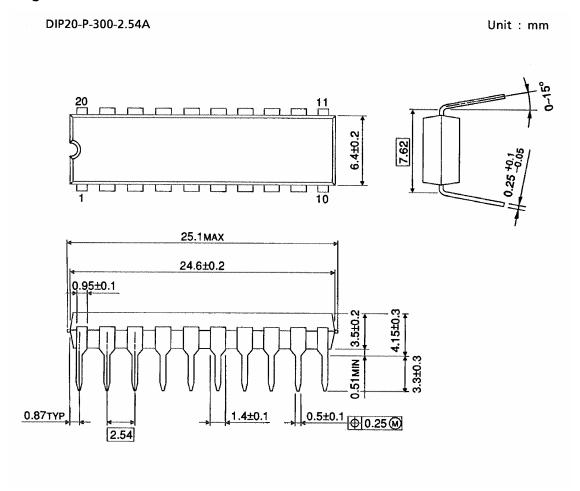
Average operating current can be obtained by the equation:

$$I_{CC (opr)} = C_{PD} \cdot V_{CC} \cdot f_{IN} + I_{CC}/8 (per F/F)$$

And the total  $C_{\mbox{\scriptsize PD}}$  when n pcs. of flip flop operate can be gained by the following equation:

$$C_{PD}$$
 (total) = 29 + 11·n

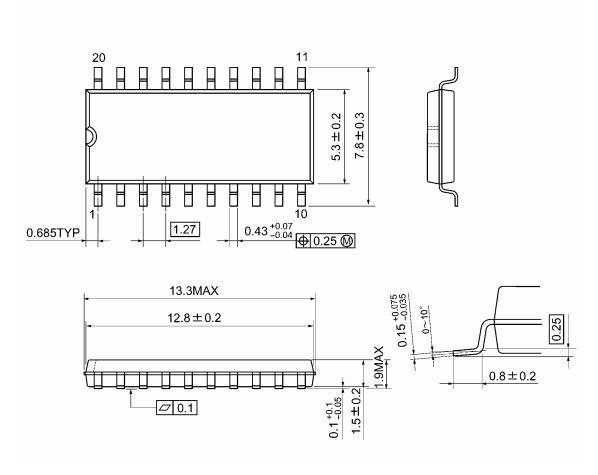
# **Package Dimensions**



Weight: 1.30 g (typ.)

# **Package Dimensions**

SOP20-P-300-1.27A Unit: mm



Weight: 0.22 g (typ.)

## **Package Dimensions**

TSSOP20-P-0044-0.65A Unit: mm  $6.4 \pm 0.2$  $0.22^{+0.09}_{-0.06}$ 0.325TYP 0.65 <del>♦</del>0.13**M** 6.9MAX 6.5±0.1 1.2MAX 0.15 +0.03 0~10 1.0±0.05  $0.1\pm0.05$ S Ø.1S (0.5)0.45~0.75

Weight: 0.08 g (typ.)

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20070701-EN GENERAL

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